

**In The Claims:**

1-230. (canceled)

- 5        231. (currently amended) A circuit ~~circuitry~~ component comprising:  
a first die having a top surface at a horizontal level;  
a bottommost metal layer over said horizontal level and extending to a place not  
over said first die, wherein said bottommost metal layer is connected to said first die;  
and  
10       a passive device over said horizontal level.

232. (currently amended) The circuit ~~circuitry~~ component in claim 231 further  
comprising a substrate joined with said first die, wherein said substrate is under said  
horizontal level.

- 15       233. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
wherein said substrate comprises polymer.

234. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
20       wherein said substrate comprises resin.

235. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
wherein said substrate comprises imide.

- 25       236. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
wherein said substrate comprises plastic.

237. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
wherein said substrate comprises thermosetting plastic.

- 30       Claim 238. (canceled)

239. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
wherein forming said substrate comprises pressing.

240. (currently amended) The circuit ~~circuitry~~ component in claim 232,  
5 wherein forming said substrate comprises injection molding.

241-242. (canceled)

243. (currently amended) The circuit ~~circuitry~~ component in claim 231 further  
10 comprising an insulating layer between said bottommost metal layer and said  
horizontal level.

244. (currently amended) The circuit ~~circuitry~~ component in claim 243,  
wherein said insulating layer comprises polyimide (PI).  
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245. (currently amended) The circuit ~~circuitry~~ component in claim 243,  
wherein said insulating layer comprises benzocyclobutene (BCB).

246. (currently amended) The circuit ~~circuitry~~ component in claim 243,  
20 wherein said insulating layer comprises a porous structure.

247. (currently amended) The circuit ~~circuitry~~ component in claim 231 further  
comprising an insulating layer over said bottommost metal layer.

248. (currently amended) The circuit ~~circuitry~~ component in claim 247,  
25 wherein said insulating layer comprises polyimide (PI).

249. (currently amended) The circuit ~~circuitry~~ component in claim 247,  
wherein said insulating layer comprises benzocyclobutene (BCB).  
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250. (currently amended) The circuit ~~circuitry~~ component in claim 247,  
wherein said insulating layer comprises a porous structure.

251. (currently amended) The circuit ~~circuitry~~ component in claim 231 further comprising an insulating layer between said passive device and said horizontal level.

5        252. (currently amended) The circuit ~~circuitry~~ component in claim 251, wherein said insulating layer comprises polyimide (PI).

253. (currently amended) The circuit ~~circuitry~~ component in claim 251, wherein said insulating layer comprises benzocyclobutene (BCB).

10        254. (currently amended) The circuit ~~circuitry~~ component in claim 251, wherein said insulating layer comprises a porous structure.

255. (currently amended) The circuit ~~circuitry~~ component in claim 231 further  
15 comprising an insulating layer over said passive device.

256. (currently amended) The circuit ~~circuitry~~ component in claim 255, wherein said insulating layer comprises polyimide (PI).

20        257. (currently amended) The circuit ~~circuitry~~ component in claim 255, wherein said insulating layer comprises benzocyclobutene (BCB).

258. (currently amended) The circuit ~~circuitry~~ component in claim 255, wherein said insulating layer comprises a porous structure.

25        259. (currently amended) The circuit ~~circuitry~~ component in claim 231, wherein said top surface comprises multiple pads.

260. (currently amended) The circuit ~~circuitry~~ component in claim 231, wherein  
30 said bottommost metal layer comprises a portion connecting multiple internal circuits of said first die.

261. (currently amended) The circuit ~~circuitry~~ component in claim 260, wherein said ~~die~~-portion is used to transmit a signal.

262. (currently amended) The circuit ~~circuitry~~ component in claim 260, wherein  
5 said ~~die~~-portion is used to provide a power voltage.

263. (currently amended) The circuit ~~circuitry~~ component in claim 260, wherein said ~~die~~-portion is used to provide a ground voltage.

10 264. (currently amended) The circuit ~~circuitry~~ component in claim 231 further comprising a second die, said bottommost metal layer being over said second die, wherein said bottommost metal layer comprises a portion connecting said first die and said second die.

15 265. (currently amended) The circuit ~~circuitry~~ component in claim 231 further comprising a film layer around said first die.

266. (currently amended) The circuit ~~circuitry~~ component in claim 265,  
wherein said film layer comprises polymer.

20 267. (currently amended) The circuit ~~circuitry~~ component in claim 265, wherein said film layer comprises epoxy.

268. (currently amended) The circuit ~~circuitry~~ component in claim 265,  
25 wherein said film layer has a surface substantially coplanar with said top surface.

269. (currently amended) The circuit ~~circuitry~~ component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises solder.

30 270. (currently amended) The circuit ~~circuitry~~ component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises gold.

271. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device comprises a resistor.

272. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
5 wherein said passive device comprises a capacitor.

273. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device comprises an inductor.

10 274. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device comprises a filter.

275. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device comprises a waveguide.

15 276. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

277. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
20 wherein said passive device is not over said first die.

278. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device is connected to a circuit trace of said bottommost metal  
layer.

25 279. (currently amended) The circuit ~~circuitry~~ component in claim 231,  
wherein said passive device is connected to said die.

Claims 280-319. (canceled)

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